# **BAS20HT1, SBAS20HT1G**

# High Voltage Switching Diode

#### **Features**

- AEC-Q101 Qualified and PPAP Capable
- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

#### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Continuous Reverse Voltage	$V_{R}$	200	Vdc
Repetitive Peak Reverse Voltage	$V_{RRM}$	200	Vdc
Continuous Forward Current	I <sub>F</sub>	200	mAdc
Peak Forward Surge Current	I <sub>FM(surge)</sub>	625	mAdc
Repetitive Peak Forward Current	I <sub>FRM</sub>	500	mA
Non-Repetitive Peak Forward Current (Square Wave, T <sub>J</sub> = 25°C prior to surge) t = 1 µs t = 1 ms t = 1 s	I <sub>FSM</sub>	5.0 2.0 0.5	Α

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR–5 Board* $T_A = 25^{\circ}C$ Derate above 25°C	P <sub>D</sub>	200 1.57	mW mW/°C
Thermal Resistance Junction-to-Ambient	$R_{\theta JA}$	635	°C/W
Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

# **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = 25°C unless otherwise noted)

Symbol

Min

Max

Unit

OFF CHARACTERISTICS					
Reverse Voltage Leakage Current (V <sub>R</sub> = 200 Vdc) (V <sub>R</sub> = 200 Vdc, T <sub>J</sub> = 150°C)	I <sub>R</sub>		1.0 100	μAdc	
Reverse Breakdown Voltage (I <sub>BR</sub> = 100 μAdc)	V <sub>(BR)</sub>	250	_	Vdc	
Forward Voltage (I <sub>F</sub> = 100 mAdc) (I <sub>F</sub> = 200 mAdc)	V <sub>F</sub>		1000 1250	mV	
Diode Capacitance (V <sub>R</sub> = 0, f = 1.0 MHz)	C <sub>D</sub>	-	5.0	pF	
Reverse Recovery Time $(I_F = I_R = 30 \text{ mAdc}, R_L = 100 \Omega)$	t <sub>rr</sub>	-	50	ns	



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# HIGH VOLTAGE SWITCHING DIODE





SOD-323 CASE 477 STYLE 1

### **MARKING DIAGRAM**



JR = Specific Device Code

M = Date Code\*

= Pb-Free Package

(Note: Microdot may be in either location)
\*Date Code orientation may vary depending upon manufacturing location.

#### ORDERING INFORMATION

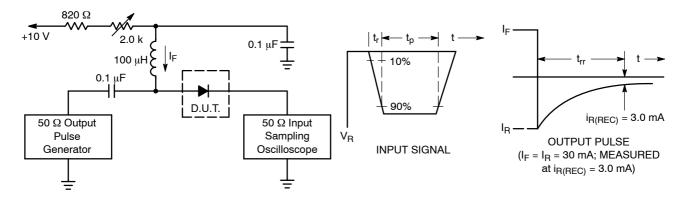
Device	Package	Shipping <sup>†</sup>
BAS20HT1G	SOD-323 (Pb-Free)	3000 / Tape & Reel
SBAS20HT1G	SOD-323 (Pb-Free)	3000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

Characteristic

<sup>\*</sup>FR-5 Minimum Pad

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Notes: 1. A 2.0  $k\Omega$  variable resistor adjusted for a Forward Current (I<sub>F</sub>) of 30 mA.

- 2. Input pulse is adjusted so  $I_{R(peak)}$  is equal to 30 mA.
- 3. t<sub>p</sub> » t<sub>rr</sub>

Figure 1. Recovery Time Equivalent Test Circuit

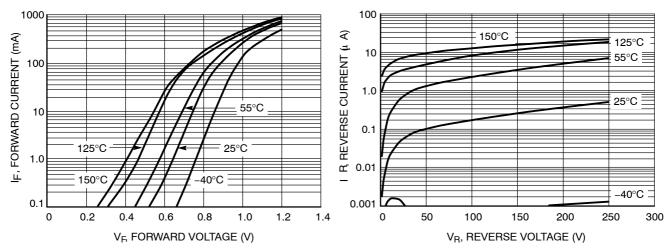


Figure 2. Forward Current

Figure 3. Leakage Current

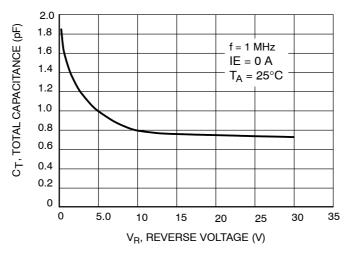
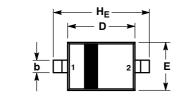


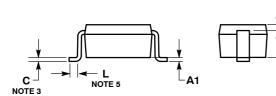
Figure 4. Total Capacitance

## BAS20HT1, SBAS20HT1G

#### PACKAGE DIMENSIONS

SOD-323 CASE 477-02 ISSUE H





#### NOTES

- DIMENSIONING AND TOLERANCING PER ANSI
   MARKET AND TOLERANC
- Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETERS.
- 3. LEAD THICKNESS SPECIFIED PER L/F DRAWING WITH SOLDER PLATING.
- DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.
- 5. DIMENSION L IS MEASURED FROM END OF RADIUS.

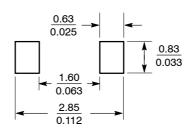
	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.80	0.90	1.00	0.031	0.035	0.040
A1	0.00	0.05	0.10	0.000	0.002	0.004
A3	0.15 REF			0.006 REF		
b	0.25	0.32	0.4	0.010	0.012	0.016
С	0.089	0.12	0.177	0.003	0.005	0.007
D	1.60	1.70	1.80	0.062	0.066	0.070
Е	1.15	1.25	1.35	0.045	0.049	0.053
L	0.08			0.003		
He	2 30	2 50	2 70	0.090	0.098	0 105

STYLE 1:

PIN 1. CATHODE (POLARITY BAND)

ANODE

#### **SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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